

Vienna, Austria - July 2019

Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Abedy, Yossuf		Pulse Electronics	1	1	1	1	4
Abramson, David	Texas Instruments Incorporated	Texas Instruments Incorporated	1	1		1	3
Andrae, Stefan	SEI ANTech-Europe GmbH	SEI ANTech-Europe GmbH	1	1	1	1	4
Anslow, Peter	Ciena	Ciena	1	1	1	1	4
Aono, Michikazu	Yazaki Corporation	Yazaki Corporation	1	1	1	1	4
Araki, Nobuyasu	Yazaki Corporation	YAZAKI	1	1	1	1	4
Aydin, Arkin	Nokia	Nokia	1	1	1		3
Baggett, Tim	Microchip Technology, Inc.	Microchip Technology, Inc.	1	1	1	1	4
Bains, Amrik	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1		3
Baumgartner, Steven	Avera Semiconductor	Avera Semiconductor		1	1	1	3
Beecroft, Jon	Cray Ltd	Cray Inc		1	1	1	3
Ben-Artzi, Liav	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.		1	1	1	3
Beruto, Piergiorgio	Canova Tech S.r.l.	Canova Tech Srl	1	1	1		3
Bhagwat, Gitesh	Analog Devices Inc.	Analog Devices Inc.	1	1	1	1	4
Bouse, David	Tektronix	Tektronix Communications	1	1	1	1	4
Brandt, David	Rockwell Automation	Rockwell Automation	1	1	1	1	4
Braun, Ralf-Peter	Deutsche Telekom AG	Deutsche Telekom AG	1	1	1	1	4
Brillhart, Theodore	Fluke Corporation	Fluke Corporation	1	1	1	1	4
Brooks, Paul	Viavi solutions GmbH	Viavi Solutions	1	1	1	1	4
Brueckner, Klemens	Audi AG	Audi AG	1	1	1	1	4
Butter, Adrian	Avera Semiconductor	Avera Semiconductor	1	1	1	1	4
Carlson, Steven	High-Speed Design Inc.	Robert Bosch GmbH	1	1	1	1	4
Carty, Clark	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1		1	3
Chang, Jacky	Hewlett Packard Enterprise	Hewlett-Packard Development Company	1	1	1	1	4
Chang, Xin	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Chang, Yongmao	Inphi Corporation	Source Photonics		1	1		2
Chen, Song	ZTE Corporation	ZTE Corporation				1	1
Choi, Eunmin	Daegu Gyeongbuk Institute of Science and Technology	Daegu Gyeongbuk Institute of Science and Technology	1	1	1	1	4
Choudhury, Golam	OFS	OFS	1	1	1	1	4
D'Ambrosia, John	Futurewei Technologies	Futurewei (Subsidiary of Huawei)	1	1	1	1	4
Darshan, Yair	Microchip Technology, Inc.	Microsemi Corporation	1	1	1	1	4
Dawe, Piers J G	Mellanox Technologies	Mellanox Technologies	1	1	1	1	4

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Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Dawson, Fred	Chemours Canada Company	Chemours Canada Company	1	1	1	1	4
Deandrea, John	Finisar Corporation	Finisar Corporation	1	1	1		3
den Besten, Gerrit	NXP Semiconductors	NXP Semiconductors	1	1	1	1	4
DeSanti, Claudio	Google	Google	1	1	1	1	4
Diminico, Christopher	M C Communications, LLC	Panduit Corp.	1	1		1	3
Dinh, Thuyen	Pulse Electronics	Pulse Electronics		1	1	1	3
Donahue, Curtis	University of New Hampshire InterOperat	UNH-IOL	1	1	1	1	4
Du, Liang	Google	Google	1	1	1	1	4
Dudek, Michael	Marvell	Marvell	1	1	1	1	4
Effenberger, Frank	Huawei Technologies Co. Ltd	Futurewei Technologies	1			1	2
Engel, Andreas	TE Connectivity	TE Connectivity	1	1	1	1	4
Estes, David	Spirent Communications	Spirent Communications	1	1	1	1	4
Eyal, Massad	Valens Semiconductor	Valens Semiconductor	1	1	1	1	4
FAn, DAWEI	HUAWEI	Huawei Technologies Co., Ltd	1	1	1	1	4
farjad, ramin	Aquantia	Aquantia	1	1	1		3
Faure, Jean Philippe	Progilon	Panasonic Corporation	1	1	1	1	4
Ferretti, Vincent	Corning Incorporated	Corning Incorporated	1	1	1	1	4
Franchuk, Brian	Emerson Automation Solutions	Emerson Automation Solutions	1	1	1	1	4
Frlan, Edward	Semtech Ltd	Semtech Ltd	1	1	1	1	4
Fukuoka, Takashi	AutoNetworks Technologies Ltd.	AutoNetworks Technologies Ltd.; Sumito	1	1	1	1	4
Gardner, Mike	Molex Incorporated	Molex Incorporated	1	1	1	1	4
Ghiasi, Ali	Ghiasi Quantum LLC	Ghiasi Quantum LLC		1	1	1	3
Gong, Zhigang	O-Net Communications Ltd.	O-Net Communications Ltd.	1	1	1	1	4
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.	1		1	1	3
Goto, Hideki	Toyota Motor Corporation	Toyota Motor Corporation	1	1	1	1	4
Graber, Steffen	Pepperl+Fuchs GmbH	Pepperl+Fuchs GmbH	1	1	1	1	4
Grau, Olaf	Robert Bosch GmbH	Robert Bosch GmbH	1	1		1	3
Grow, Robert	RMG Consulting	RMG Consulting	1	1	1	1	4
Gubow, Martin	Keysight Technologies	Keysight Technologies	1	1	1	1	4
GUO, YONG	ZTE Corporation	ZTE Corporation	1	1	1	1	4
Gustlin, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Hajduczenia, Marek	Charter Communications	Charter Communications	1	1	1	1	4

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He, Xiang	HUAWEI	HUAWEI	1	1	1	1	4
Healey, Adam	Broadcom Inc.	Broadcom Inc.	1	1	1	1	4
Heck, Howard	Intel Corporation	Intel Corporation	1	1	1		3
Hernandez, Emily	Cellink Corporation	Cellink Corporation	1	1	1	1	4
Hess, David	CORD DATA	CORD DATA	1	1	1	1	4
Holden, Brian	Kandou Bus	Kandou Bus	1	1	1		3
Hormmeyer, Bernd	Phoenix Contact	Phoenix Contact	1	1	1	1	4
HUANG, ZHAORUI	China Mobile Communications Corporat	IEEE	1	1	1	1	4
HYAKUTAKE, YASUHIRO	Adamant Namiki Precision Jewel Co., Ltd	Adamant Namiki Precision Jewel Co., Ltd	1	1	1	1	4
Ingham, Jonathan	Foxconn Interconnect Technology	Foxconn Interconnect Technology	1		1	1	3
Islinger, Tobias	Infineon Technologies AG	Infineon Technologies AG	1	1	1		3
Isono, Hideki	FUJITSU	Fujitsu Optical Components Limited	1	1	1	1	4
Issenhuth, Tom	Issenhuth Consulting, LLC	Huawei Technologies Co. Ltd	1		1	1	3
Ito, Hiroaki	Yazaki Corporation	Yazaki Corporation	1	1	1	1	4
Jackson, Kenneth	Sumitomo Electric Device Innovations, U	Sumitomo Electric Industries, LTD		1	1	1	3
Jimenez, Andrew	Anixter Inc.	Anixter Inc.	1	1	1		3
Johnson, John	Broadcom Limited	Broadcom Limited	1	1	1		3
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Kabra, Lokesh	Synopsys, Inc.	Synopsys, Inc.	1	1	1		3
Kadry, Haysam	Ford Motor Company	Ford Motor Company	1	1	1	1	4
Kagami, Manabu	Nagoya Institute of Technology	Nagoya Institute of Technology (NITech)	1	1	1	1	4
Kang, Su Won	GCT Semiconductor, Inc.	Velonect	1	1	1		3
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Kasapi, Athanasios	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.		1	1	1	3
Kawatsu, Yasuaki	APRESIA Systems	APRESIA Systems	1	1	1	1	4
Kim, Yongbum	NIO	NIO	1	1	1	1	4
Kimber, Eric	Semtech Ltd	Semtech Ltd	1	1	1	1	4
Klempa, Michael	University of New Hampshire InterOpera	University of New Hampshire InterOpera	1	1	1	1	4
Knittle, Curtis	Cable Television Laboratories Inc. (Cable	Cable Television Laboratories Inc. (Cable	1	1	1	1	4
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1		3
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation		1	1	1	3

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Koczwara, Wojciech	Rockwell Automation	Rockwell Automation	1	1	1	1	4
Koeppendoerfer, Erwin	LEONI Kabel GmbH	LEONI	1	1	1	1	4
Kondo, Taiji	MegaChips Corporation	MegaChips Corporation	1	1	1	1	4
Koppermueller, Daniel	MD Elektronik GmbH	MD Elektronik GmbH	1	1	1	1	4
Kramer, Glen	Broadcom Corporation	Broadcom Corporation		1	1	1	3
Kumada, Taketo	Yazaki Corporation	Yazaki Corporation		1	1	1	3
Kurata, Kazuhiko	AIO Core CO.,LTD.	AIO Core	1	1			2
Kurobe, Akio	Panasonic Corporation of North America	Panasonic Corporation	1	1	1		3
Lackner, Hans	QoSCom GmbH	QoSCom - Quality in Communications - G	1	1	1	1	4
Lambrecht, Frank	Gigamon, Inc.	Gigamon, Inc.	1	1	1	1	4
Landsman, David		Western Digital Corporation			1		1
Laubach, Mark	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise	1	1	1	1	4
Le Cheminant, Greg	Keysight Technologies	Keysight Technologies	1	1	1	1	4
Lee, Han Hyub	ETRI	ETRI	1	1	1		3
Lewis, David	Lumentum Inc.	Lumentum Inc.	1	1		1	3
Lewis, Jon	Dell EMC	Dell EMC	1	1	1	1	4
Li, Mike-Peng	Intel Corporation	Intel Corporation	1	1	1	1	4
Lim, Jane	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Lin, Alex	MediaTek	MediaTek Inc.	1	1	1	1	4
Iiu, dekun	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd	1	1	1		3
Lo, William	Marvell Semiconductor, Inc.	Axonne Inc.		1	1	1	3
Lu, Yuchun	Huawei Technologies Co. Ltd	HUAWEI	1	1	1	1	4
Lusted, Kent	Intel Corporation	Intel Corporation	1	1	1	1	4
Madgar, Zahy	Valens Semiconductor	Valens Semiconductor	1	1	1	1	4
Maguire, Valerie	The Siemon Company	The Siemon Company	1	1	1	1	4
Maki, Jeffery	Juniper Networks, Inc.	Juniper Networks, Inc.	1	1	1	1	4
Maniloff, Eric	Ciena Corporation	Ciena Corporation		1	1	1	3
Marques, Flavio	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC	1	1	1	1	4
Marris, Arthur	Cadence Design Systems, Inc.	Cadence Design Systems, Inc.	1	1	1	1	4
mash, chris	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.		1	1	1	3
MASUDA, TAKEO	OITDA	OITDA	1	1	1	1	4

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Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Matheus, Kirsten	BMW Group	BMW Group		1	1	1	3
Matoglu, Erdem	Amphenol Corporation	Amphenol Corporation		1	1	1	3
McCarthy, Mick	Analog Devices Inc.	Analog Devices Inc.	1	1	1	1	4
Mcclellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1	1	1	4
McMillan, Larry	Western Digital Corporation	Western Digital Corporation	1	1		1	3
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.	1	1		1	3
mi, guangcan	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Miller, Martin	Microchip Technology, Inc.	Microchip Technology, Inc.	1	1	1	1	4
Mueller, Harald	Endress + Hauser	Endress + Hauser	1	1	1	1	4
Mueller, Sina	Hirschmann Automation and Control, Inc	Hirschmann Automation and Control, Inc		1	1	1	3
Mueller, Thomas	Rosenberger	Rosenberger	1	1	1	1	4
Muller, Shimon	Axalume, Inc.	Axalume, Inc.		1	1	1	3
Nadolny, James	Samtec, Inc.	Samtec	1	1	1	1	4
Nakamoto, Edward	Spirent Communications	Spirent Communications	1	1	1	1	4
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1			2
Nicholl, Shawn	Xilinx	Xilinx	1	1	1	1	4
Nikolich, Paul	Self	SAMSUNG				1	1
Nomura, Takumi	Honda R&D	Honda R&D	1	1	1		3
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Ofelt, David	Juniper Networks, Inc.	Juniper Networks, Inc.	1	1	1	1	4
Ohni, Josef	MD Elektronik GmbH	MD Elektronik	1	1	1	1	4
Okabe, Ryo	Fujitsu Optical Components Limited	Fujitsu Optical Components Limited	1	1	1	1	4
Palkert, Thomas	EIC	Molex-Macom		1	1		2
Pandey, Sujan	NXP Semiconductors	NXP Semiconductors	1	1	1	1	4
Pardo, Carlos	Knowledge Development for POF SL	KDPOF		1		1	2
Parsons, Earl	CommScope, Inc.	CommScope, Inc.	1	1	1	1	4
Pelletier, Erick	TeraXion	TeraXion			1		1
peng, wanquan	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1		3
Pham, Phong	US Conec, Ltd.	US Conec, Ltd.	1	1	1		3
Pittala, Fabio		Huawei Technologies Duesseldorf GmbH		1	1	1	3
Pitwon, Richard	Resolute Photonics	AIO Core	1	1	1		3
Pohl, Christopher	Beckhoff Automation	Beckhoff Automation	1	1	1	1	4

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Name	Employer	Affiliation	Mon	Tue	Wed	Thu	Credit
Powell, William	Nokia	Nokia	1	1	1	1	4
Pozzebon, Dino	Microchip Technology, Inc.	Microchip Technology, Inc.	1	1	1	1	4
Preibisch, Jan	Nexperia	Nexperia	1	1			2
Preis, Roland	MD Elektronik GmbH	MD Elektronik GmbH	1	1	1	1	4
Ran, Adee	Intel Corporation	Intel Corporation	1	1	1	1	4
Rechtman, Zvi	Mellanox Technologies	Mellanox Technologies		1	1	1	3
Remein, Duane	Futurewei Technologies	Futurewei Technologies	1		1	1	3
Rennie, David	Synopsys, Inc.	Synopsys, Inc.	1	1	1	1	4
Rettig, Thomas	Beckhoff Automation	Beckhoff Automation		1	1	1	3
Rodenkirchen, Robert	Yazaki Corporation	Yazaki Europe Ltd	1	1	1	1	4
Rusch, Christian	TE Connectivity	TE Connectivity	1	1	1	1	4
Salehi, Hamid	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1	1		3
Schicketanz, Dieter	Self	CONSULTANT; Reutlingen University	1	1	1	1	4
Schmidt, Rainer	HARTING Electronics GmbH	Harting			1		1
Schmitt, Matthew	Cable Television Laboratories Inc. (Cable	Cable Television Laboratories Inc. (Cable	1	1	1	1	4
Sedarat, Hossein	Ethernovia	Ethernovia	1	1	1		3
Shariff, Masood	CommScope, Inc.	CommScope, Inc.	1	1	1	1	4
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC	1	1	1	1	4
shirani, ramin	Ethernovia	Ethernovia	1	1	1		3
Shrikhande, Kapil	Innovium Inc.	Innovium		1	1	1	3
Shuai, Jialong	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Sluyski, Michael	Acacia Communications	Acacia Communications		1	1		2
Sommers, Scott	Molex Incorporated	Molex Incorporated	1	1	1		3
SONG, HOSEUNG	Daegu Gyeongbuk Institute of Science and	Daegu Gyeongbuk Institute of Science and		1	1		2
Sprague, Edward	Infinera Corporation	Infinera Corporation	1	1	1	1	4
Stassar, Peter	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Stewart, Heath	Analog Devices Inc.	Analog Devices Inc.	1	1	1	1	4
Sun, Junqing	Credo Semiconductor	Credo Semiconductor	1	1	1		3
Sun, Liyang	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Sun, Yanbin	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
TAKAHARA, TOMOO	FUJITSU LABORATORIES LIMITED	FUJITSU LIMITED	1	1	1	1	4
Takahashi, Satoshi	Self Employed	Self Employed	1	1	1	1	4

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Takahashi, Tadashi	Nitto Denko Corporation	Nitto Denko Corporation	1	1	1	1	4
Takayama, Kazuya	Nitto Denko Corporation	Nitto Denko Corporation	1	1	1	1	4
Takefman, Michael	Inphi Corporation	Inphi Corporation	1	1	1	1	4
TAKEUCHI, JUNICHI	JAE Electronics, Inc	JAE Electronics, Inc.	1	1	1		3
Thompson, Geoffrey	GraCaSI S.A.	INDEPENDENT		1	1	1	3
Tooyserkani, Pirooz	Cisco Systems, Inc.	Cisco Systems, Inc.	1	1	1	1	4
Tracy, Nathan	TE Connectivity	TE Connectivity	1	1	1	1	4
Tremblay, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise	1	1	1	1	4
Trowbridge, Stephen	Nokia	Nokia	1	1	1	1	4
Tse, Richard	Microchip Technology, Inc.	Microchip Technology, Inc.	1			1	2
TSENG, TA CHIN	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.	1	1	1	1	4
Tu, Mike	Broadcom Corporation	Broadcom Corporation	1	1	1	1	4
Twombly, Jeff	Credo Semiconductor	Credo Semiconductor		1	1	1	3
Ulrichs, Ed	Source Photonics	Source Photonics	1	1	1	1	4
Vakilian, Kambiz	Broadcom Corporation	Broadcom Corporation	1	1	1		3
Vernickel, Ricky	LEONI	LEONI	1	1	1	1	4
Walker, Clinton	Intel Corporation	Intel Corporation	1	1	1	1	4
Walter, Edward	AT&T	AT&T	1	1	1	1	4
Wang, Tongtong	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Wechsler, Christoph	Audi AG	Audi AG	1	1	1	1	4
Wei, Dong	Futurewei Technologies	Futurewei Technologies	1	1	1	1	4
Welch, Brian	Luxtera	Luxtera	1	1			2
Wendt, Matthias	Signify (Philips Lighting)	Signify	1	1		1	3
Wienckowski, Natalie	General Motors Company	General Motors Company	1	1	1	1	4
Wu, Chengbin	ZTE Corporation	ZTE Corporation	1	1	1	1	4
Wu, Dance	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.			1	1	2
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.	1	1	1	1	4
Wucher, Markus	Endress + Hauser Flowtec AG	Endress + Hauser	1	1	1	1	4
Xu, Dayin	Rockwell Automation	Rockwell Automation	1	1	1	1	4
Xu, Yu	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd		1	1	1	3
Yam, Julius	Semtech Ltd	Semtech Ltd		1	1	1	3
Yamamoto, Shuto	Nippon Telegraph and Telephone Corpor	Nippon Telegraph and Telephone Corpor	1	1	1	1	4

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Young, James	CommScope, Inc.	CommScope	1	1	1	1	4
Yseboodt, Lennart	Signify	Signify	1	1		1	3
Zerna, Conrad	Fraunhofer IIS	Fraunhofer IIS	1		1	1	3
Zhang, Xingxin	Huawei Technologies Co. Ltd	Huawei Technologies Co., Ltd	1	1	1	1	4
Zhu, Chunhui	Huawei Technologies Co. Ltd	Futurewei Technologies	1	1	1	1	4
Zhuang, Yan	Huawei Technologies Co. Ltd	Huawei Technologies Co. Ltd	1	1	1	1	4
Zielinski, Martin	Emerson Electric Co.	Emerson Process Management	1	1	1	1	4
Zimmerman, George	CME Consulting	CME Consulting/ADI, APL Group, Aquant	1	1	1	1	4
Zinner, Helge	Continental Automotive Systems AG	Continental Automotive Systems AG	1				1
Zivny, Pavel	Tektronix, Inc.	Tektronix, Inc.	1	1	1	1	4
Zou, Gaoling	Maxim Integrated Products	Maxim Integrated Products		1	1	1	3